MC100LVE111

3.3V ECL 1:9 Differential Clock Driver

The MC100LVE111 is a low skew 1−to−9 differential driver, designed with clock distribution in mind. The MC100LVE111's function and performance are similar to the popular MC100E111, with the added feature of low voltage operation. It accepts one signal input, which can be either differential or single−ended if the V_{BB} output is used. The signal is fanned out to 9 identical differential outputs.

The LVE111 is specifically designed, modeled and produced with low skew as the key goal. Optimal design and layout serve to minimize gate to gate skew within a device, and empirical modeling is used to determine process control limits that ensure consistent t_{pd} distributions from lot to lot. The net result is a dependable, guaranteed low skew device.

To ensure that the tight skew specification is met it is necessary that both sides of the differential output are terminated into 50 Ω, even if only one side is being used. In most applications, all nine differential pairs will be used and therefore terminated. In the case where fewer than nine pairs are used, it is necessary to terminate at least the output pairs on the same package side as the pair(s) being used on that side, in order to maintain minimum skew. Failure to do this will result in small degradations of propagation delay (on the order of 10−20 ps) of the output(s) being used which, while not being catastrophic to most designs, will mean a loss of skew margin.

The MC100LVE111, as with most other ECL devices, can be operated from a positive V_{CC} supply in PECL mode. This allows the LVE111 to be used for high performance clock distribution in +3.3 V systems. Designers can take advantage of the LVE111's performance to distribute low skew clocks across the backplane or the board. In a PECL environment, series or Thevenin line terminations are typically used as they require no additional power supplies. For systems incorporating GTL, parallel termination offers the lowest power by taking advantage of the 1.2 V supply as a terminating voltage. For more information on using PECL, designers should refer to Application Note AN1406/D.

The V_{BB} pin, an internally generated voltage supply, is available to this device only. For single−ended input conditions, the unused differential input is connected to V_{BB} as a switching reference voltage. V_{BB} may also rebias AC coupled inputs. When used, decouple V_{BB} and V_{CC} via a 0.01 μF capacitor and limit current sourcing or sinking to 0.5 mA. When not used, V_{BB} should be left open.

Features

- 200 ps Part−to−Part Skew
- 50 ps Output−to−Output Skew
- The 100 Series Contains Temperature Compensation
- PECL Mode Operating Range: V_{CC} = 3.0 V to 3.8 V with V_{EE} = 0 V
- NECL Mode Operating Range: V_{CC} = 0 V with V_{EE} = −3.0 V to −3.8 V
- Internal Input Pulldown Resistors
- Q Output will Default LOW with Inputs Open or at V_{EE}
- These are Pb−Free Devices*

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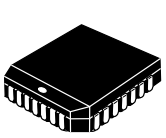
MARKING DIAGRAM*



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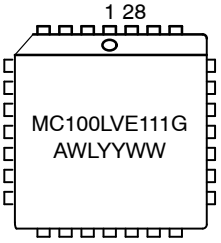
CASE 776



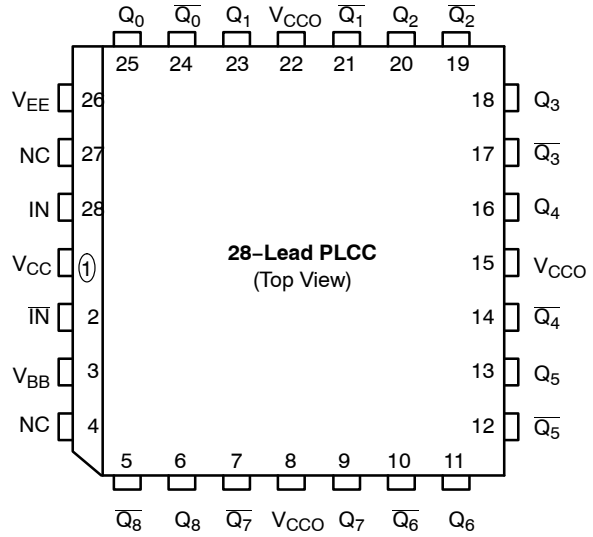
A	= Assembly Location
WL	= Wafer Lot
YY	= Year
WW	= Work Week
G	= Pb−Free Package

*For additional marking information, refer to Application Note AND8002/D.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



Warning: All V_{CC}, V_{CCO}, and V_{EE} pins must be externally connected to Power Supply to guarantee proper operation.

Figure 1. Pinout (Top View) **and Logic Diagram**

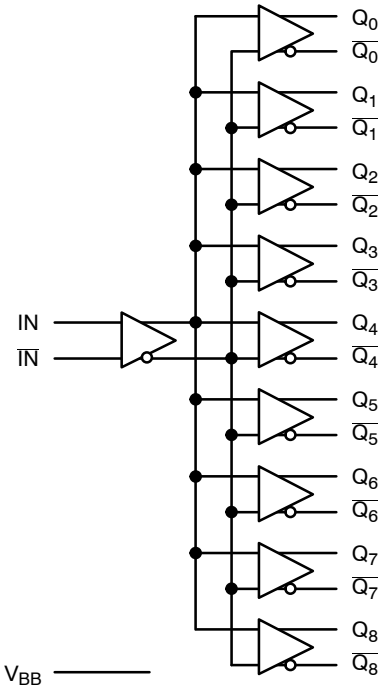


Figure 2. Logic Symbol

Table 1. PIN DESCRIPTION

Pin	Function
IN, $\overline{IN}$	ECL Differential Input Pair
Q_0, $\overline{Q_0}$–Q_8, $\overline{Q_8}$	ECL Differential Outputs
V_{BB}	Reference Voltage Output
V_{CC}, V_{CCO}	Positive Supply
V_{EE}	Negative Supply
NC	No Connect

Table 2. ATTRIBUTES

Characteristics		Value
Internal Input Pulldown Resistor		75 kΩ
Internal Input Pullup Resistor		N/A
ESD Protection	Human Body Model Machine Model	> 2 kV > 200 V
Moisture Sensitivity, Indefinite Time Out of Drypack (Note 1)		Level 3
Flammability Rating	Oxygen Index: 28 to 34	UL 94 V−0 @ 0.125 in
Transistor Count		250
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test		

1. For additional information, see Application Note AND8003/D.

Table 3. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V_{CC}	PECL Mode Power Supply	V_{EE} = 0 V		8 to 0	V
V_{EE}	NECL Mode Power Supply	V_{CC} = 0 V		−8 to 0	V
V_I	PECL Mode Input Voltage NECL Mode Input Voltage	V_{EE} = 0 V V_{CC} = 0 V	$V_I \leq V_{CC}$ $V_I \geq V_{EE}$	6 to 0 −6 to 0	V V
I_{out}	Output Current	Continuous Surge		50 100	mA mA
I_{BB}	V_{BB} Sink/Source			± 0.5	mA
T_A	Operating Temperature Range			−40 to +85	°C
T_{stg}	Storage Temperature Range			−65 to +150	°C
θ_{JA}	Thermal Resistance (Junction−to−Ambient)	0 lfpm 500 lfpm	PLCC−28 PLCC−28	63.5 43.5	°C/W °C/W
θ_{JC}	Thermal Resistance (Junction−to−Case)	Standard Board	PLCC−28	22 to 26 ± 5%	°C/W
T_{sol}	Wave Solder Pb Pb−Free	<2 to 3 sec @ 248°C <2 to 3 sec @ 260°C		265 265	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Table 4. LVPECL DC CHARACTERISTICS V_{CC} = 3.3 V; V_{EE} = 0 V (Note 2)

		−40°C			25°C			85°C			
Symbol	Characteristic	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Unit
I_{EE}	Power Supply Current		55	66		55	66		65	78	mA
V_{OH}	Output HIGH Voltage (Note 3)	2215	2345	2420	2275	2345	2420	2275	2345	2420	mV
V_{OL}	Output LOW Voltage (Note 3)	1490	1595	1680	1490	1595	1680	1490	1595	1680	mV
V_{IH}	Input HIGH Voltage (Single−Ended)	2135		2420	2135		2420	2135		2420	mV
V_{IL}	Input LOW Voltage (Single−Ended)	1490		1825	1490		1825	1490		1825	mV
V_{BB}	Output Voltage Reference	1.92		2.04	1.92		2.04	1.92		2.04	V
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 4)	1.8		2.9	1.8		2.9	1.8		2.9	V
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	0.5			0.5			0.5			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

2. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary ±0.3 V.
3. Outputs are terminated through a 50 Ω resistor to V_{CC} − 2.0 V.
4. V_{IHCMR} min varies 1:1 with V_{EE}, maximum varies 1:1 with V_{CC}. V_{IHCMR} is defined as the range within which the V_{IH} level may vary, with the device still meeting the propagation delay specification. The V_{IL} level must be such that the peak to peak voltage is less than 1.0 V and greater than or equal to V_{PP}(min).

Table 5. LVNECL DC CHARACTERISTICS V_{CC} = 0 V; V_{EE} = −3.3 V (Note 5)

		−40°C			25°C			85°C			
Symbol	Characteristic	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Unit
I_{EE}	Power Supply Current		55	66		55	66		65	78	mA
V_{OH}	Output HIGH Voltage (Note 6)	−1085	−955	−880	−1025	−955	−880	−1025	−955	−880	mV
V_{OL}	Output LOW Voltage (Note 6)	−1810	−1705	−1620	−1810	−1705	−1620	−1810	−1705	−1620	mV
V_{IH}	Input HIGH Voltage (Single−Ended)	−1165		−880	−1165		−880	−1165		−880	mV
V_{IL}	Input LOW Voltage (Single−Ended)	−1810		−1475	−1810		−1475	−1810		−1475	mV
V_{BB}	Output Voltage Reference	−1.38		−1.26	−1.38		−1.26	−1.38		−1.26	V
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 7)	−1.5		−0.4	−1.5		−0.4	−1.5		−0.4	V
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	0.5			0.5			0.5			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

5. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary ±0.3 V.
6. Outputs are terminated through a 50 Ω resistor to V_{CC} − 2.0 V.
7. V_{IHCMR} min varies 1:1 with V_{EE}, maximum varies 1:1 with V_{CC}. V_{IHCMR} is defined as the range within which the V_{IH} level may vary, with the device still meeting the propagation delay specification. The V_{IL} level must be such that the peak to peak voltage is less than 1.0 V and greater than or equal to V_{PP}(min).

Table 6. AC CHARACTERISTICS V_{CC} = 3.3 V; V_{EE} = 0 V or V_{CC} = 0 V; V_{EE} = −3.3 V (Note 8)

		−40°C			25°C			85°C			
Symbol	**Characteristic**	**Min**	**Typ**	**Max**	**Min**	**Typ**	**Max**	**Min**	**Typ**	**Max**	**Unit**
f_{max}	Maximum Toggle Frequency		> 1.5			> 1.5			> 1.5		GHz
t_{PLH} t_{PHL}	Propagation Delay to Output IN (Differential Configuration) (Note 9) sIN (Single−Ended) (Note 10)	 400 350		 650 700	 440 390		 630 680	 445 395		 635 685	ps
t_{skew}	Within−Device Skew (Note 11) Part−to−Part Skew (Differential Configuration)			50 250			50 200			50 200	ps
t_{JITTER}	Cycle−to−Cycle Jitter		0.2	< 1		0.2	< 1		0.2	< 1	ps
V_{PP}	Input Swing (Note 12)	500		1000	500		1000	500		1000	mV
t_r/t_f	Output Rise/Fall Time (20%−80%)	200		600	200		600	200		600	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

8. V_{EE} can vary ±0.3 V.
9. The differential propagation delay is defined as the delay from the crossing points of the differential input signals to the crossing point of the differential output signals.
10. The single−ended propagation delay is defined as the delay from the 50% point of the input signal to the 50% point of the output signal.
11. The within−device skew is defined as the worst case difference between any two similar delay paths within a single device.
12. V_{PP}(min) is defined as the minimum input differential voltage which will cause no increase in the propagation delay. The V_{PP}(min) is AC limited for the E111 as a differential input as low as 50 mV will still produce full ECL levels at the output.

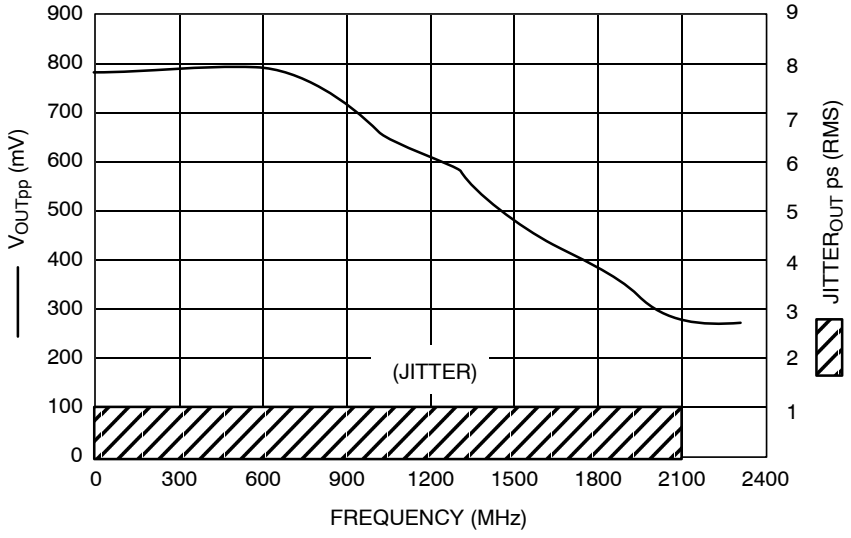


Figure 3. F_{max}/Jitter

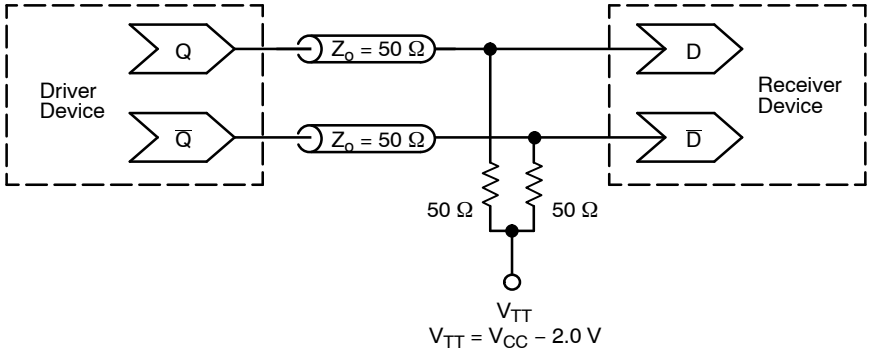


Figure 4. Typical Termination for Output Driver and Device Evaluation (See Application Note AND8020/D – Termination of ECL Logic Devices.)

ORDERING INFORMATION

Device	Package	Shipping†
MC100LVE111FNG	PLCC–28 (Pb–Free)	37 Units / Rail
MC100LVE111FNR2G	PLCC–28 (Pb–Free)	500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Resource Reference of Application Notes

AN1405/D – ECL Clock Distribution Techniques

AN1406/D – Designing with PECL (ECL at +5.0 V)

AN1503/D – ECLinPS™ I/O SPiCE Modeling Kit

AN1504/D – Metastability and the ECLinPS Family

AN1568/D – Interfacing Between LVDS and ECL

AN1672/D – The ECL Translator Guide

AND8001/D – Odd Number Counters Design

AND8002/D – Marking and Date Codes

AND8020/D – Termination of ECL Logic Devices

AND8066/D – Interfacing with ECLinPS

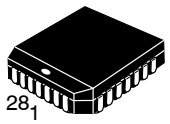
AND8090/D – AC Characteristics of ECL Devices

MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®

28 LEAD PLLC
CASE 776−02
ISSUE F

DATE 29 JUL 2008



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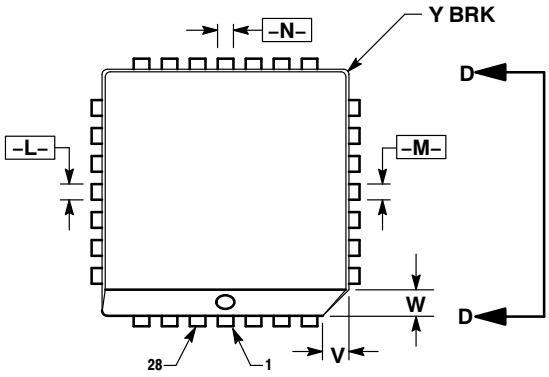
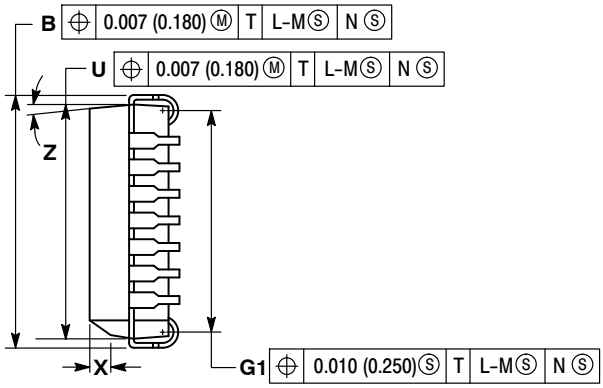
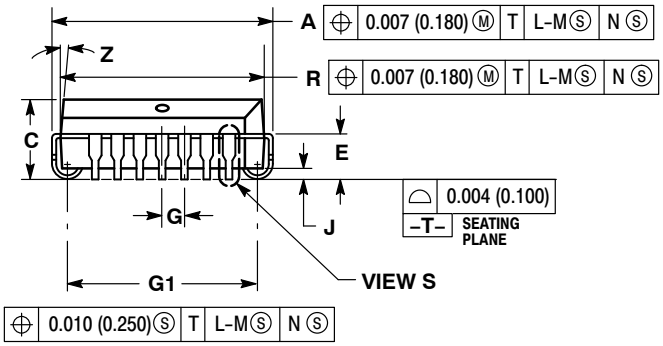
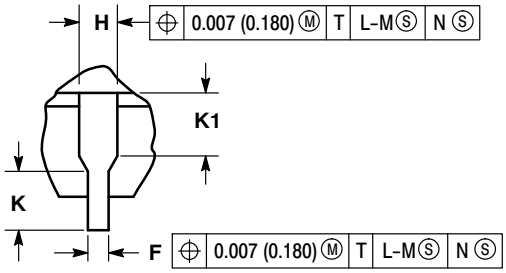




VIEW D–D



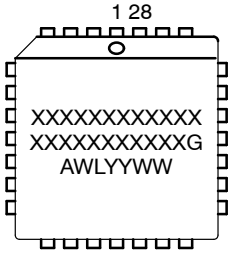


VIEW S

NOTES:
1. DATUMS –L–, –M–, AND –N– DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM –T–, SEATING PLANE.
3. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
4. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
5. CONTROLLING DIMENSION: INCH.
6. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
7. DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.485	0.495	12.32	12.57
B	0.485	0.495	12.32	12.57
C	0.165	0.180	4.20	4.57
E	0.090	0.110	2.29	2.79
F	0.013	0.021	0.33	0.53
G	0.050 BSC		1.27 BSC	
H	0.026	0.032	0.66	0.81
J	0.020	---	0.51	---
K	0.025	---	0.64	---
R	0.450	0.456	11.43	11.58
U	0.450	0.456	11.43	11.58
V	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Y	---	0.020	---	0.50
Z	2°	10°	2°	10°
G1	0.410	0.430	10.42	10.92
K1	0.040	---	1.02	---

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week
G = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

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DESCRIPTION:	**28 LEAD PLLC**	**PAGE 1 OF 1**

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